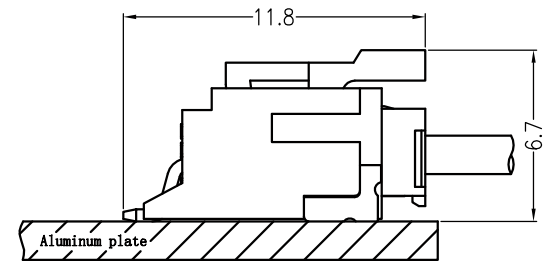
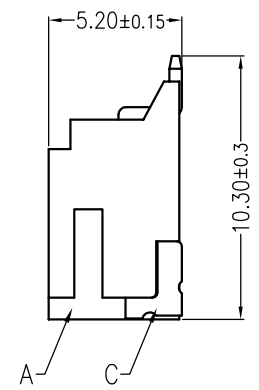
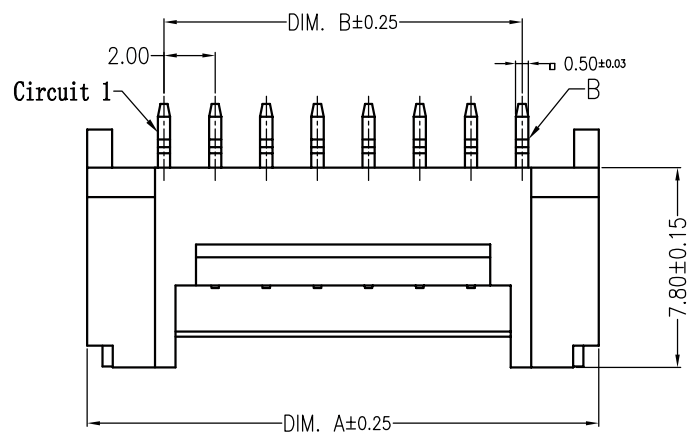
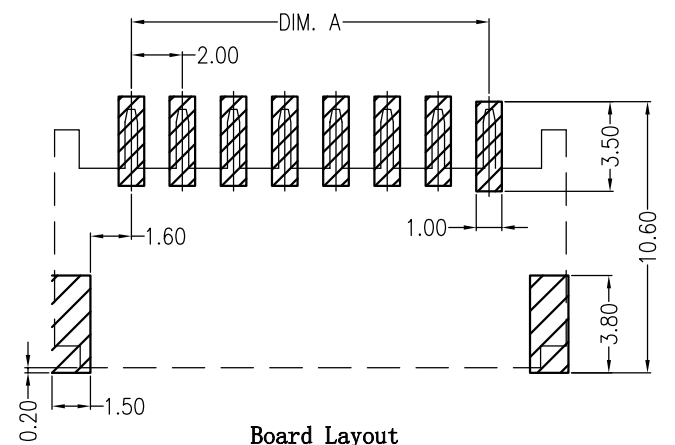
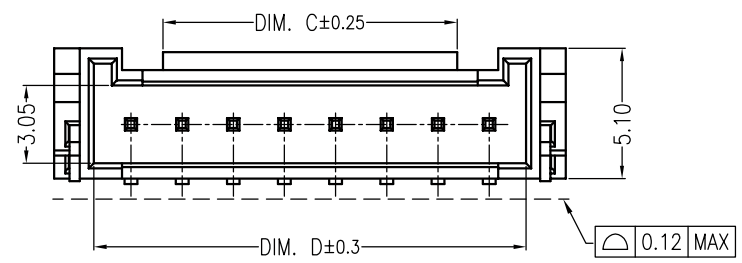
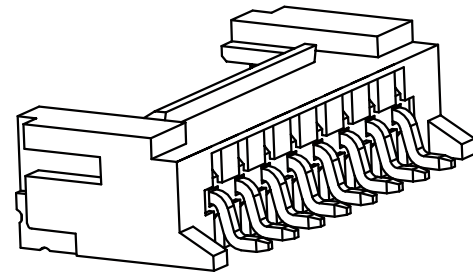


REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	吴丹平	2016.05.09
A/1		变更2、3孔基座尺寸	蒋建银	2018.04.19



Assembly Layout
主要技术参数 Main Specifications

- 线 数 (Poles): 02 to 16
- 接触电阻 (Contact resistance): ≤20mΩ
- 绝缘电阻 (Insulation resistance): ≥1000MΩ
- 额定电压 (Rated voltage): 250V AC DC
- 额定电流 (Rated current): 2.0A AC DC
- 耐 电压 (Withstand Voltage): 1000V AC/minute
- 温度范围 (Temperature Range): -25℃ ~ +105℃



Board Layout
General Tolerance: ±0.05

Circuits	Dimensions (mm)			
	DIM. A	DIM. B	DIM. C	DIM. D
02	8.00	2.00	2.70	4.75
03	10.00	4.00	3.20	6.75
04	12.00	6.00	3.50	8.90
05	14.00	8.00	5.50	10.90
06	16.00	10.00	7.50	12.90
07	18.00	12.00	9.50	14.90
08	20.00	14.00	11.50	16.90
09	22.00	16.00	13.50	18.90
10	24.00	18.00	15.50	20.90
11	26.00	20.00	15.50	22.90
12	28.00	22.00	15.50	24.90
13	30.00	24.00	15.50	26.90
14	32.00	26.00	15.50	28.90
15	34.00	28.00	15.50	30.90
16	36.00	30.00	15.50	32.90

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	SOLDER TAB	2 PCS	Brass	Sn-plated
B	CONTACT	1~16 PCS	Brass	Sn-plated
A	PEDESTAL	1 PCS	LCP/PA6T/PA9T	UL 94V-0

X.±0.5		X.±5°	USE: CUSTOMER		TITLE: 2.0mmPITCH 90°WAFER SMT TYPE
			APPD: 邵敬和		
.X±0.3		.X±2°	CHKD: 田峰		DWG NO.:
			DR: 吴丹平		
.XX±0.25		.XX±1°		SHEET 1 / 1	
---		---		UNITS: mm	